

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A method for testing printed ~~print~~ circuit boards comprising the ~~following~~ steps of:
 - (a) determining ~~measuring~~ all points to be tested on a printed ~~the print~~ circuit board;
 - (b) manufacturing a testing board having protrusive metal points ~~according to the information obtained in step (a), the testing board having~~ corresponding to the points to be tested on the circuit board and at least one set of connector holes for connectors;
 - (c) connecting the protrusive metal points ~~in step (b)~~ to the connector holes on the testing board;
 - (d) inserting connectors in the connector holes and connecting each connector to a test node in a tester; ~~connecting the testing board having protrusive metal points to a tester and the protruding metal points connected to test node in the tester, and~~
 - (e) inserting at least one pressure sensitive conductive rubber layer between the testing board ~~having protruding metal points~~ and the printed ~~print~~ circuit board to be tested; [[,]] and
 - (f) testing the points to be tested on the printed circuit board by pressuring the pressure sensitive conductive layer using a pressure from a press of the tester being transferred to the pressure sensitive conductive rubber layer via electrically connect the protrusive metal points and the points to be tested.

2. (Currently Amended) The method as claimed in Claim 1, wherein ~~the measurement~~ in step (a) ~~is made by software~~ is used to determine all points on the printed circuit board to be tested.
3. (Currently Amended) The method as claimed in Claim 1, wherein the connector holes ~~[[hole]]~~ in step (b) ~~[[is]]~~ are located at a side of the testing board.
4. (Currently Amended) The method as claimed in Claim 1, wherein coordinates of the protrusive metal points in step (b) are the same as those of the points to be tested on the printed ~~print~~ circuit board.
5. (Currently Amended) The method as claimed in Claim 1, wherein ~~the connection~~ connecting the protrusive metal points to the connector holes on the testing board in step (c) is made by way of layout.
6. (Currently Amended) The method as claimed in Claim 1, wherein ~~the connection~~ connecting each connector to a test node in step (d) is made by flat cables.
7. (Original) The method as claimed in Claim 1, wherein the tester in step (d) is a dedicated tester.

8-21. (Cancelled).